



**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q81064

Hideo WATANABE, et al.

Appln. No.: 10/823,798

Group Art Unit: 3711

Confirmation No.: 4687

Examiner: Raeann Gordon

Filed: April 14, 2004

For: GOLF BALL

**SUBMISSION OF EXECUTED DECLARATION UNDER 37 C.F.R. §1.132**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Submitted herewith is a copy of an executed Declaration Under 37 C.F.R. §1.132 signed by Hideo WATANABE.

Respectfully submitted,

A handwritten signature in black ink.

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WASHINGTON OFFICE  
**23373**  
CUSTOMER NUMBER

Date: June 23, 2005



ON THE U.S. PATENT AND TRADEMARK OFFICE

APPLICANT : WATANABE ET AL.

SERIAL NO.: 10/823,798

FILED: April 14, 2004

FOR: GROUP: 3711

EXAMINER: Raeann Gorden

D E C L A R A T I O N

Honorable Commissioner of Patents and Trademarks Washington, D.C. 20231

Sir,

I, Hideo Watanabe, resident of c/o Bridgestone Sports Co., Ltd.,  
M&D center Chichibu, 20, Ohnohara, Chichibu-shi, Saitama-ken, Japan do  
hereby declare that:

1. I was graduated from Master Course of Mechanical Engineering,  
Faculty of Science and Technology of Tokyo University of Science, Japan  
in March 1990. From April 1990 to 1993, I was employed by Bridgestone  
Corporation, and in April 1993, I was transferred from Bridgestone  
Corporation to Bridgestone Sports Co., Ltd., the assignee of the  
above-identified application. I have been engaged in research and  
development relating to sporting goods such as golf balls in the laboratory  
of the Company.

2. I am one of the named inventors of the above-identified

application and I am familiar with the subject matter disclosed in said application.

3. In order to show the feature of the present invention, I conducted the following experiment.

[Experiment]

The object of the experiment is to measure the melt flow rate (MFR) of a cover resin composition of E1 to E5 of Table 1 disclosed in USP 5,830,086 (Hayashi et al.).

Melt flow rate of the cover resin compositions of E1 to E5 were measured in accordance with JIS K7210 (1999), that is, under conditions: test temperature 190°C and test load 21.2 N (2.16 kgf). The results are as follows.

Table I

Cover (Outer layer)	E1	E2	E3	E4	E5
Himilan 1605	-	-	50	30	30
Himilan 1706	-	-	50	-	-
Himilan 1601	50	50	-	-	-
Himilan 1557	50	50	-	50	50
Himilan 1856	-	-	-	20	20
Surlyn	-	-	-	-	-
Melt Flow Rate (MFR)	2.1	2.1	1.7	2.7	2.7

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Dated this 13<sup>th</sup> day of May, 2005

Hideo Watanabe